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ISSUE CLASSIFICATION	
Class	Subclass

PATENT NUMBER

U.S. UTILITY Patent Application

O.I.P.E.	PATENT DATE
AK 572 SCANNED 0.A. AG	4/1/1

APPLICATION NO. 09/705237	CONT/PRIOR F	CLASS 264	SUBCLASS	ART UNIT 1732 122	EXAMINER Nguyen
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APPLICANTS
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Die used for resin-sealing and molding an electronic component.

TIME

PTO-2040
12/99

ISSUING CLASSIFICATION

Continued on Issue Slip Inside File Jacket

<input type="checkbox"/> TERMINAL DISCLAIMER		DRAWINGS			CLAIMS ALLOWED	
		Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.					NOTICE OF ALLOWANCE MAILED	
		_____ (Assistant Examiner) (Date)				
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent No. _____					ISSUE FEE	
		_____ (Primary Examiner) (Date)			Amount Due	Date Paid
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.					ISSUE BATCH NUMBER	
		_____ (Legal Instruments Examined) (Date)				

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